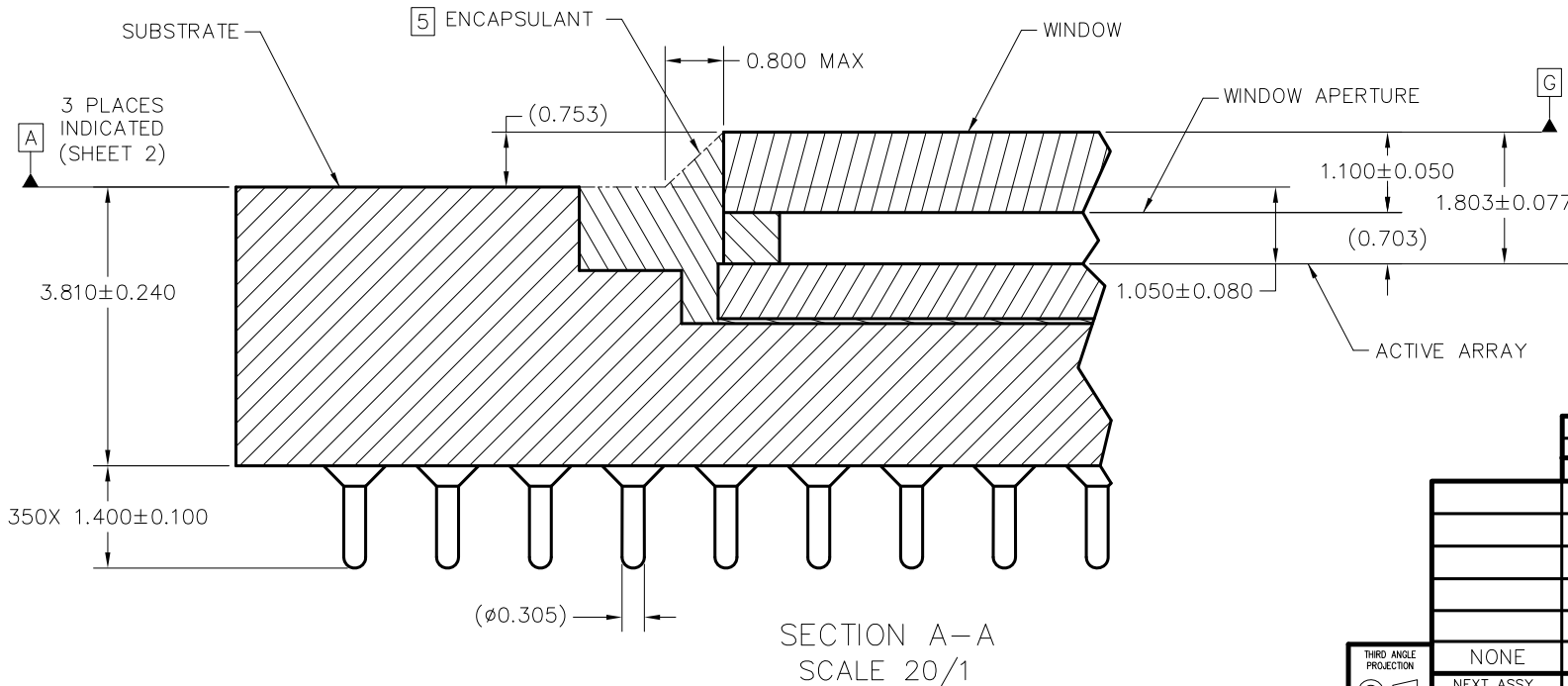
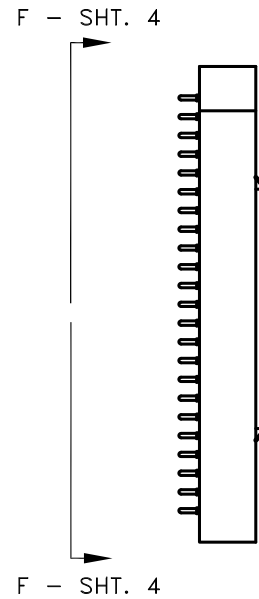
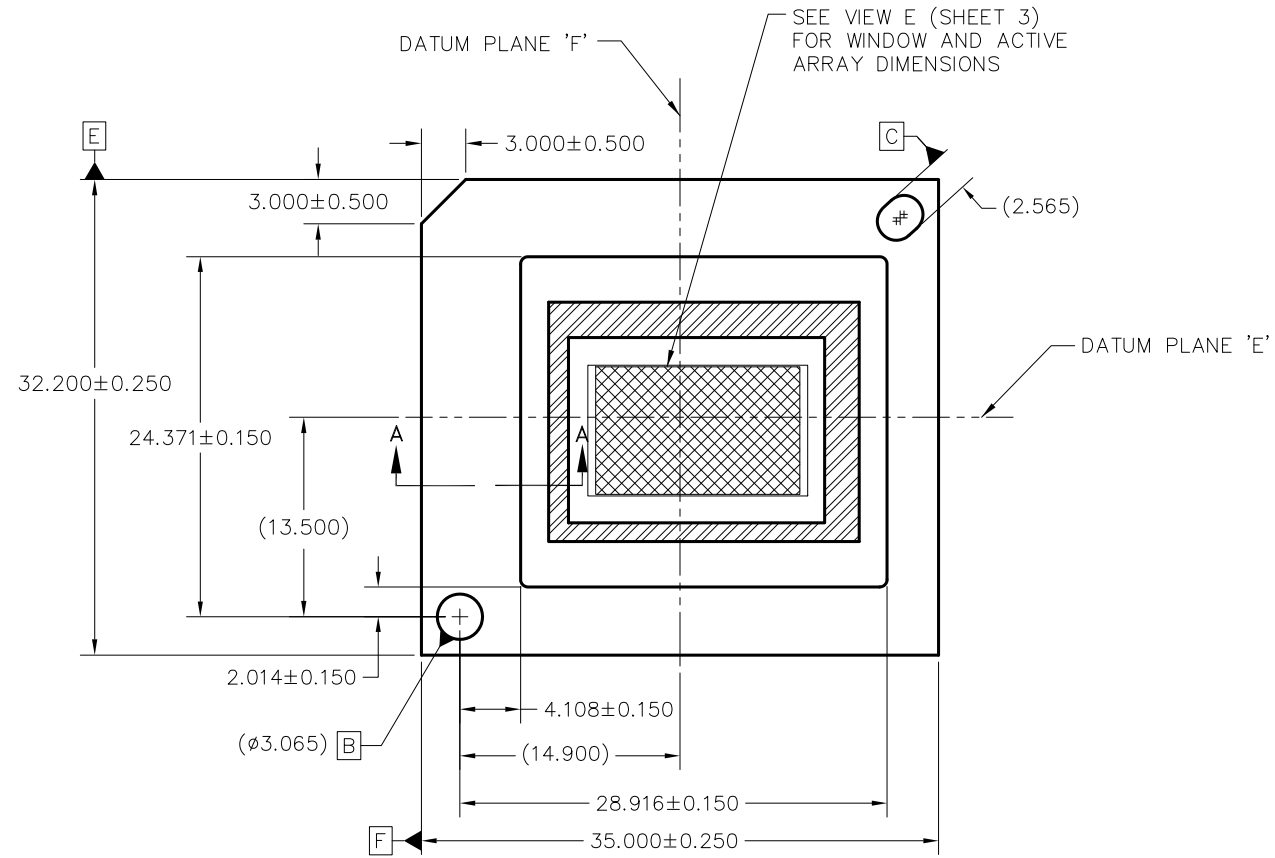
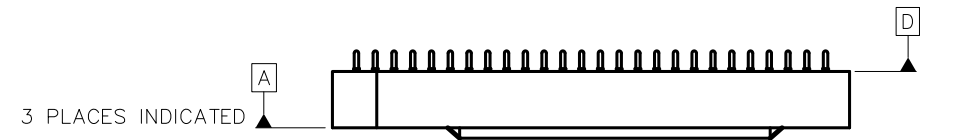


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2146604, INITIAL RELEASE	11/11/2014	M. AVERY
B	ECO 2147302, ADD GLASS DIMENSIONS	12/17/2014	F. ARMSTRONG
C	ECO 2156970, CHG NUMERICAL IDENTIFIER TO 317	03/17/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 3 SUBSTRATE SYMBOLIZATION PAD AND PLATING AT BOTTOM OF DATUMS B AND C HOLES ARE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 4 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 5 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 6 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 7 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.



SECTION A-A  
SCALE 20/1

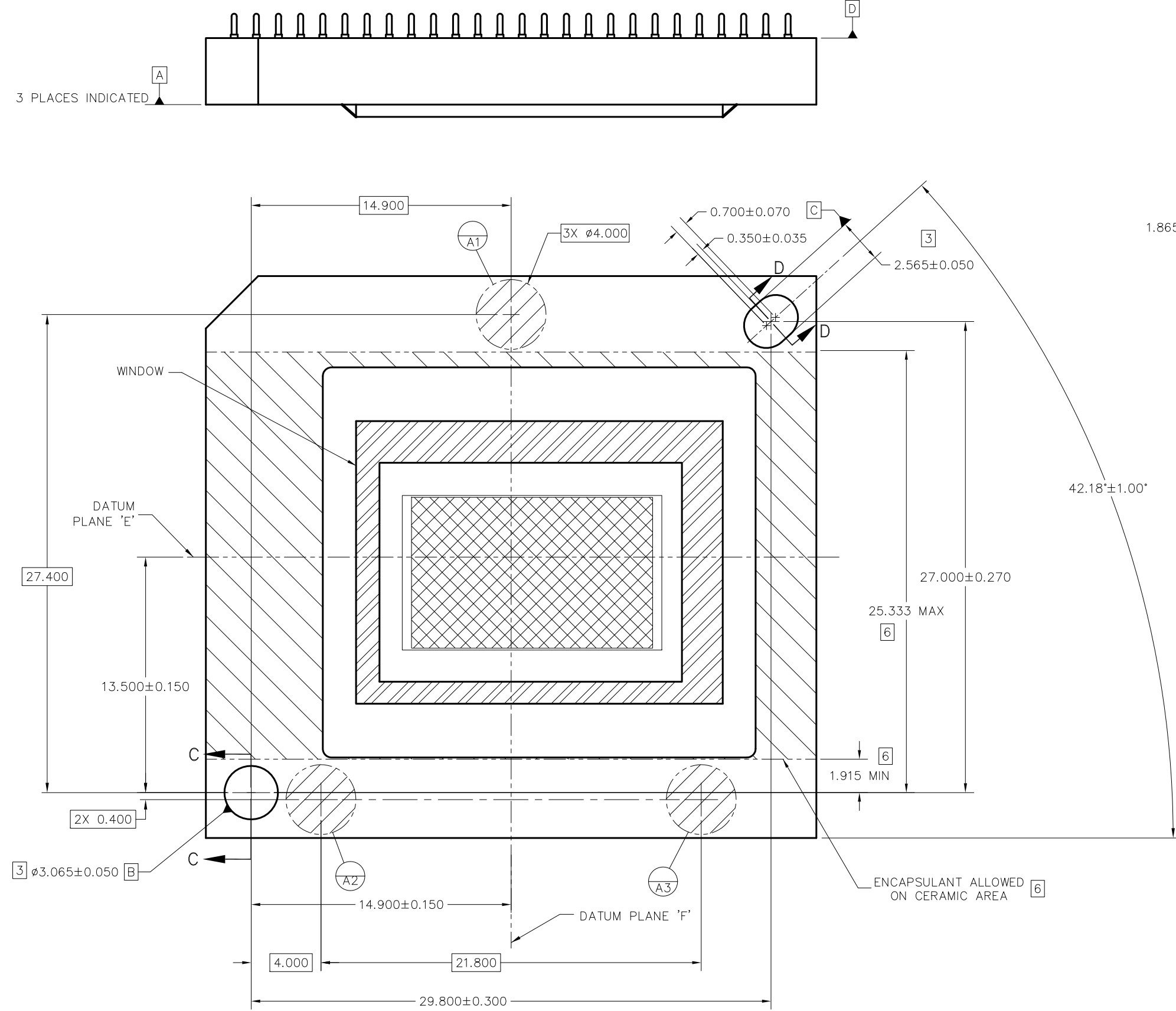
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

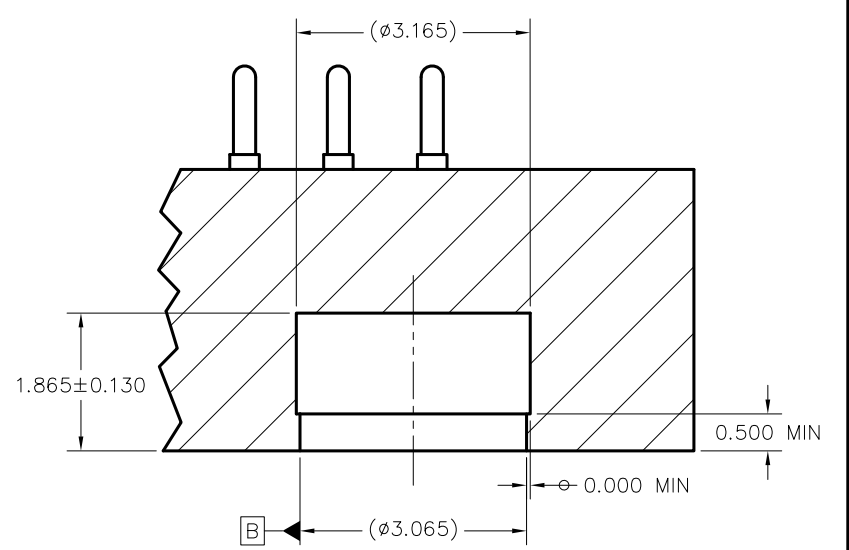
PARTS LIST		DATE	
ENGR	M. AVERY	11/05/2014	
QA	F. ARMSTRONG	11/05/2014	
QA	P. KONRAD	11/13/2014	
QA	BRIAN RAY	11/12/2014	
COE	M. DORAK	11/12/2014	
	STEVEN SUSI	11/13/2014	

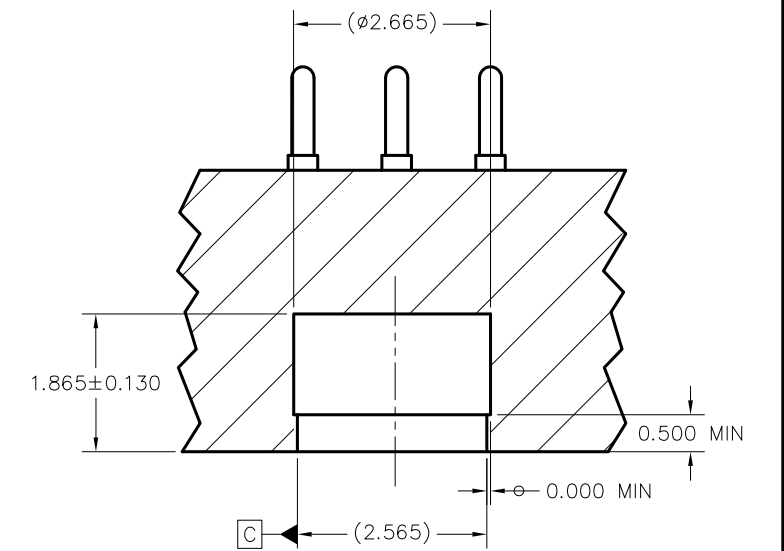
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ±0.25 3 PLACE DECIMALS ±0.50		TEXAS INSTRUMENTS Dallas, Texas	
REMOVE ALL BURRS AND SHARP EDGES INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES PARENTHEICAL INFO FOR REF ONLY		ICD, MECHANICAL, DMD .64 WQXGA HB MTRP 2XLVDS SERIES 610 (FYF PACKAGE)	
THIRD ANGLE PROJECTION	NONE	0314DA	SIZE D
NEXT ASSY	USED ON	APPLICATION	DRAWING NO 2514358
			SCALE 4/1
			SHEET 1 OF 4



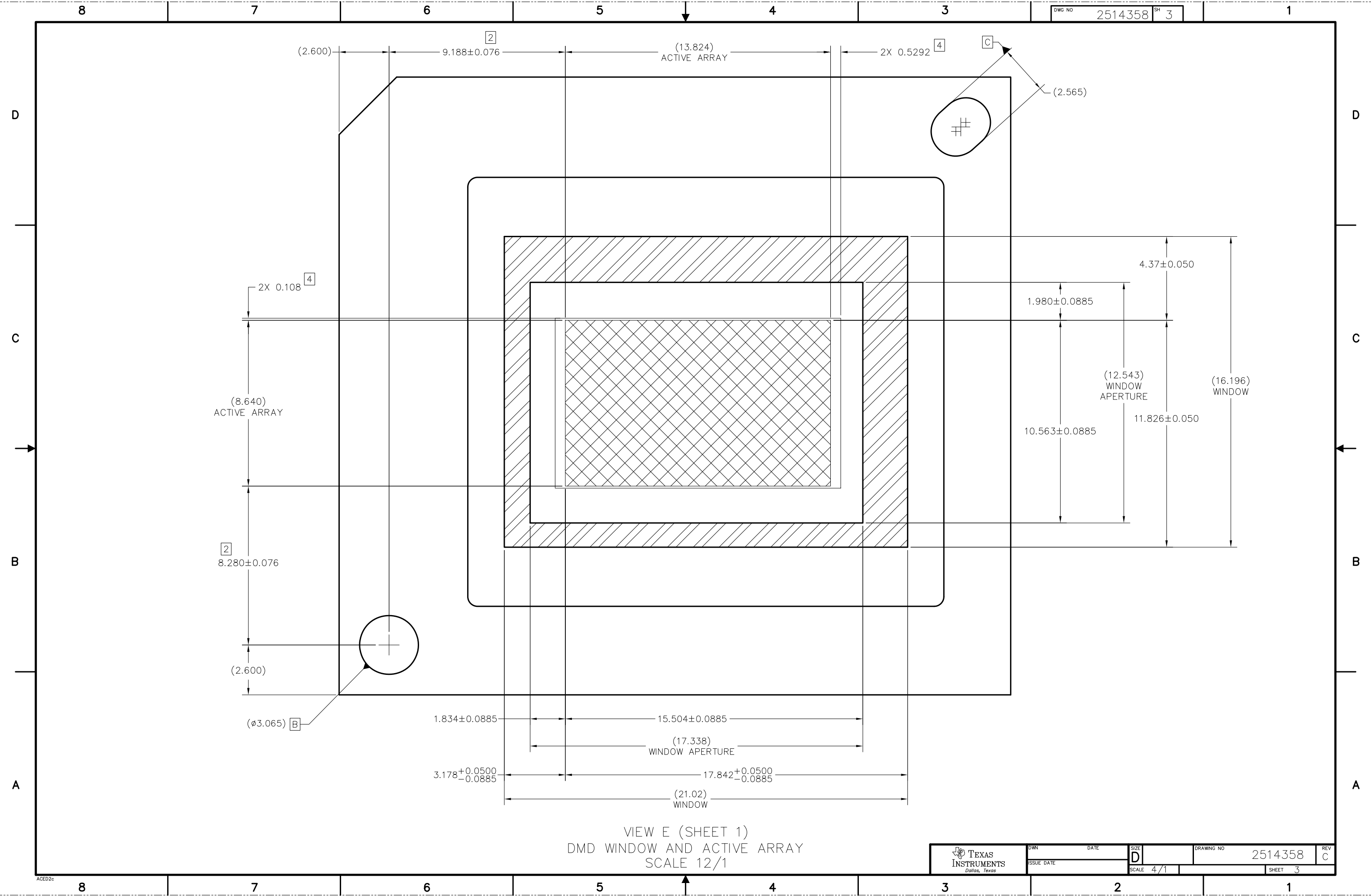
VIEW B  
DATUMS AND ENCAPSULANT ALLOWABLE AREA  
SCALE 8/1



SECTION C-C  
DATUM B  
SCALE 16/1



SECTION D-D  
DATUM C  
SCALE 16/1



(2.600)

9.188±0.076

(13.824) ACTIVE ARRAY

2X 0.5292

(2.565)

2X 0.108

(8.640) ACTIVE ARRAY

8.280±0.076

(2.600)

(ø3.065)

1.834±0.0885

15.504±0.0885

(17.338) WINDOW APERTURE

3.178<sup>+0.0500</sup>/<sub>-0.0885</sub>

17.842<sup>+0.0500</sup>/<sub>-0.0885</sub>

(21.02) WINDOW

10.563±0.0885

1.980±0.0885

4.37±0.050

11.826±0.050

(12.543) WINDOW APERTURE

(16.196) WINDOW

VIEW E (SHEET 1)  
DMD WINDOW AND ACTIVE ARRAY  
SCALE 12/1

D

C

B

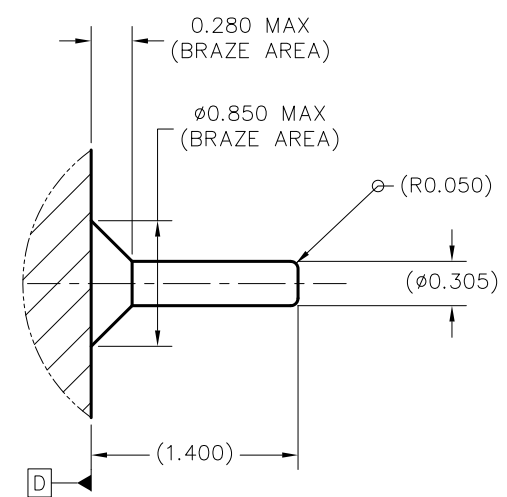
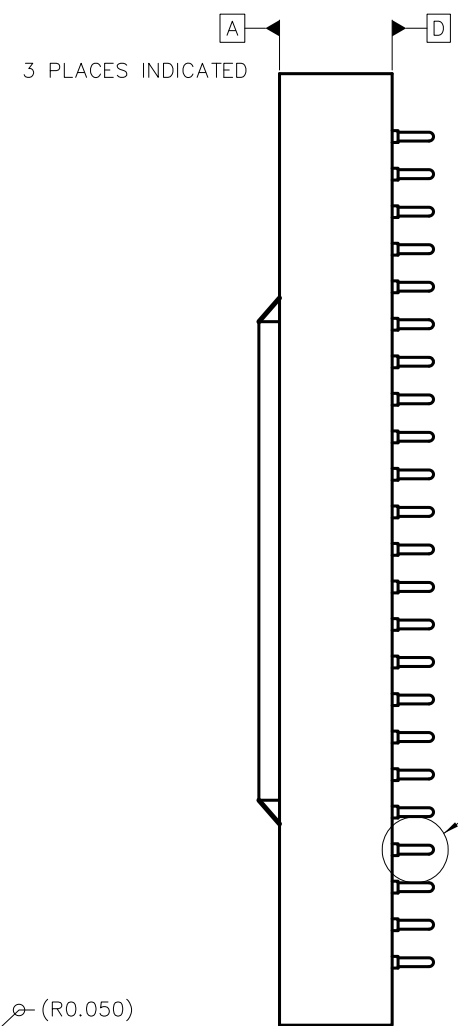
A

D

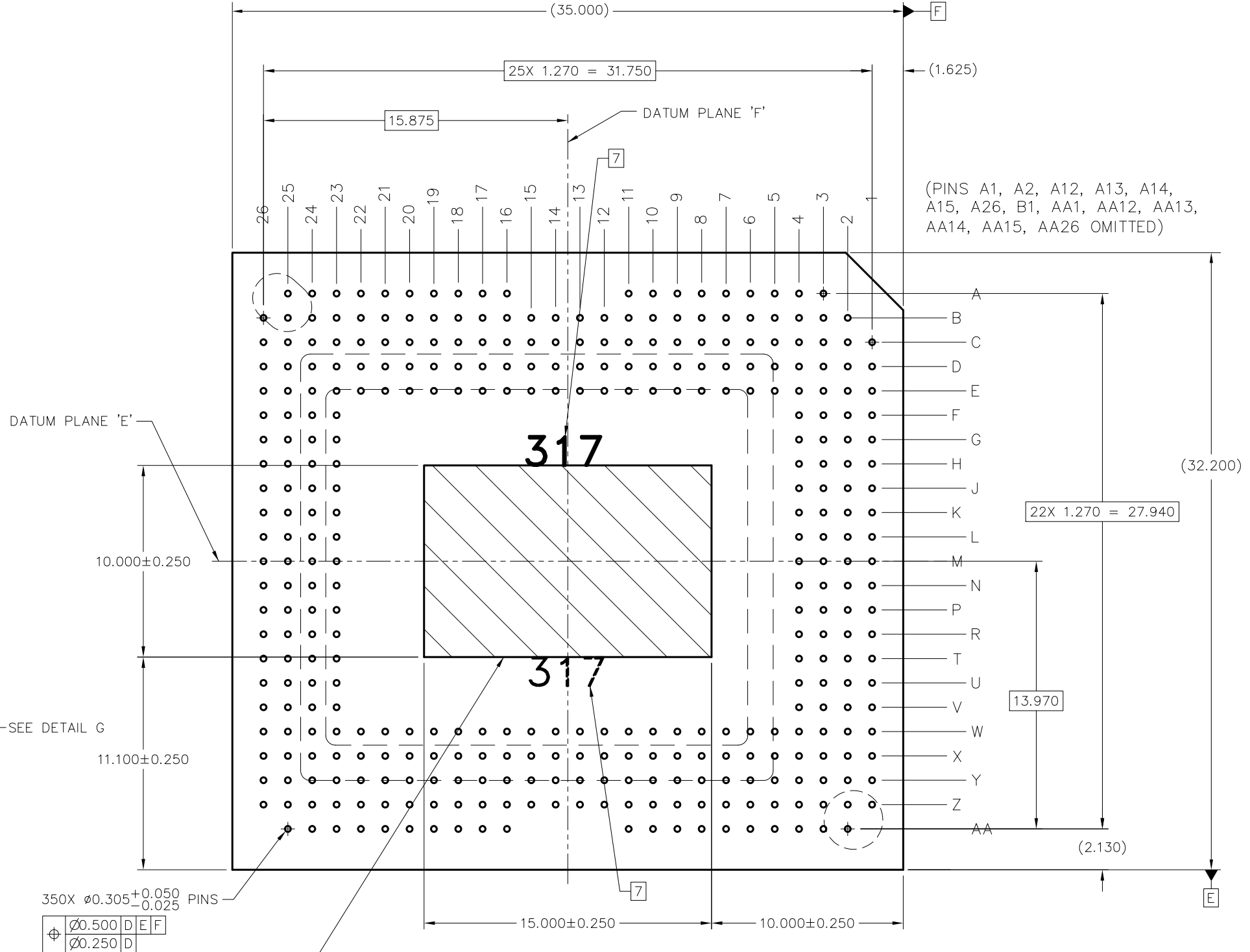
C

B

A



DETAIL G (350 PLACES)  
PIN & BRAZE DIMENSIONS  
SCALE 40/1



VIEW F-F (SHEET 1)  
PINS AND SYMBOLIZATION PAD  
SCALE 8/1

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